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(74) Agent: OLSON, Timothy, J.; Wiggin & Dana LLP, One Century Tower, New Haven, CT 06508-1832 (US).

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(71) Applicant (for all designated States except US): **ADVANCED INTERCONNECT TECHNOLOGIES LIMITED** [MU/MU]; a company incorporated under the laws of the Republic of Mauritius, Valmet (Mauritius) Limited, 608 St. James Court, St. Denis Street, Port Louis (MU).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **JUSKEY, Frank, J.** [US/US]; 1706 Imperial Palm Drive, Apopka, FL 32712 (US). **LAU, Daniel, K.** [US/US]; 395 Stonecrest Drive, San Francisco, CA 94132 (US). **THOMPSON, Lawrence, R.** [US/US]; 5675 Keymar Drive, San Jose, CA 95123 (US).

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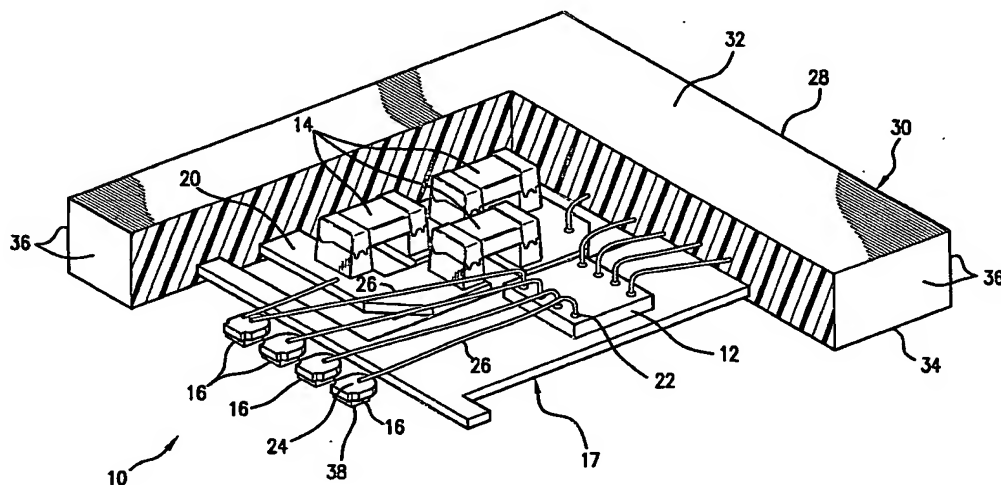
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(54) Title: LEAD FRAME WITH INCLUDED PASSIVE DEVICES



(57) Abstract: An semiconductor device package (10) includes a semiconductor device (die) (12) and passive devices (14) electrically connected to a common lead frame (17). The lead frame (17) is formed from a stamped and/or etched metallic structure and includes a plurality of conductive leads (16) and a plurality of interposers (20). The passive devices (14) are electrically connected to the interposers (20), and I/O pads (22) on the die (12) are electrically connected to the leads (16). The die (12), passive devices (14), and lead frame (17) are encapsulated in a molding compound (28), which forms a package body (30). Bottom surfaces (38) of the leads (16) are exposed at a bottom face (34) of the package (10).



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*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*